

**AMENDMENTS TO THE CLAIMS**

**Listing of claims:**

This listing of claims replaces all prior versions and listings of claims in the application.

Claim 1 (Original) A method of mounting an electronic component on a substrate, comprising:

placing the electronic component on the substrate with a solid support interposed between the electronic component and the substrate so as to space a terminal conductor of the electronic component from a corresponding terminal pad on the substrate;

melting a conductive bonding material on the terminal pad; and thereafter

melting the solid support so as to move down the electronic component toward the substrate, thereby contacting the terminal conductor with the conductive bonding material melting on the corresponding terminal pad.

Claim 2 (Original) The method according to claim 1, wherein said solid support is made of a thermoplastic resin material having a melting point higher than that of the conductive bonding material.

Claim 3 (Original) The method according to claim 1, wherein said conductive bonding material comprises solder particles dispersed in a flux including an organic solvent.

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Claim 4 (Original) The method according to claim 1, wherein said solid support has an adherent property on its surface.

Claims 5-19 (Canceled)

Claim 20 (New) The method according to claim 1, wherein the electronic component drops toward the substrate based on its own weight in response to melting of the solid support.